









PRODUCT DATASHEET



- ► PTH/THT Lamp
- ► 4.1mm Bullet Head 8.7t
- ► Warm White (3700K)

N0W59L96





APPLICATIONS:

Indicator

Signal Light

Switch

FEATURES:



Forward Current: 20mA Forward Voltage (typ.): 3.0V

Bullet Head Lamp

Luminous Intensity (typ.): 32000mcd@20mA

Colour: Warm White

Colour Temperature: 3700K (X=0.4000; Y=0.4100)

Viewing Angle: 12°

Electrostatics Discharge (ESD): 200V

Materials:

Die: InGaN

Resin: Epoxy (Water Clear)

Operating Temperature: -40~+85°C

Storage Temperature: -40~+100°C

Grouping Parameters:

Forward voltage

Luminous intensity

CIE Chromaticity

Soldering Methods: Hand; Soldering Heat (DIP)

Packing: max.500pcs/bulk



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	25	mA
Peak Forward Current Duty 1/10@1KHz	I _{FP}	100	mA
Reverse Current @5V	I _R	10	μΑ
Power Dissipation	P _D	85	mW
Electrostatics Discharge	ESD	200	V
Operating Temperature	T _{OPR}	-40~+85	°C
Storage Temperature	T _{STG}	-40~+100	°C

Electrical & Optical Characteristics (Ta=25°C)

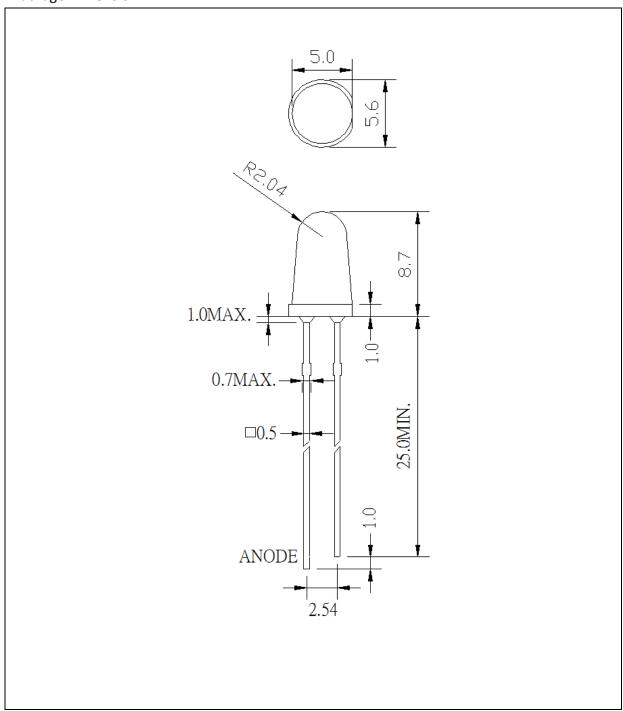
Parameter	Symbol		Values		Unit	Test	
Parameter	Зуппоп	Min.	Typ. Max.		Offic	Condition	
Forward Voltage	V_{F}	2.8	3.0	3.4	V	I _F =20mA	
Luminous Intensity	lv	16500	32000	50000	mcd	I _F =20mA	
Chromaticity	Х		0.4000			I _F =20mA	
Coordinates	Υ		0.4100				
Colour Temperature	ССТ		3700		К	I _F =20mA	
Viewing Angle	2θ _{1/2}		12		deg	I _F =20mA	

^{1.} Luminous intensity (I_V) ±15%, Forward Voltage (V_F) ±0.1V



OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.25mm, unless otherwise noted.



BINNING GROUPS:

Forward Voltage Classifications (I_F = 20mA):

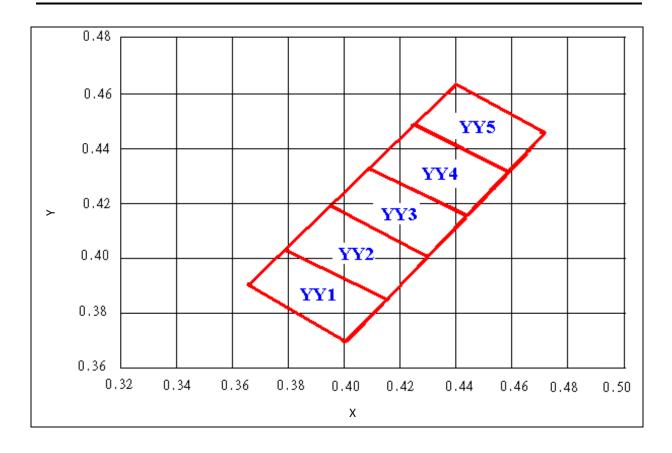
Code	Min.	Max.	Unit
J-1	2.8	2.9	
J-2	2.9	3.0	
K-1	3.0	3.1	V
K-2	3.1	3.2	V
L-1	3.2	3.3	
L-2	3.3	3.4	

Luminous Intensity Classifications (I_F = 20mA):

Code	Min.	Max.	Unit
23	16500	25000	
24	25000	32000	mad
25	32000	40000	mcd
26	40000	50000	



CIE CHROMATICITY DIAGRAM:



Chromaticity Coordinates Classifications (I_F = 20mA):

	1	1	2		3		4	
	Х	Υ	Х	Υ	Х	Υ	Х	Υ
YY1	0.3650	0.3900	0.3800	0.4050	0.4180	0.3850	0.4000	0.3700
YY2	0.3800	0.4050	0.3950	0.4200	0.4310	0.4010	0.4180	0.3850
YY3	0.3950	0.4200	0.4100	0.4350	0.4440	0.4160	0.4310	0.4010
YY4	0.4100	0.4350	0.4250	0.4500	0.4600	0.4300	0.4440	0.4160
YY5	0.4250	0.4500	0.4400	0.4650	0.4730	0.4460	0.4600	0.4300

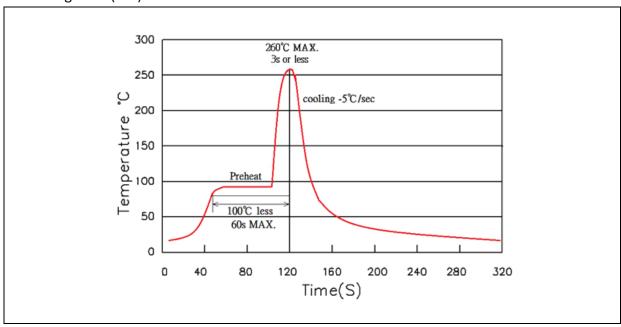


RECOMMENDED SOLDERING PROFILE:

Hand Solder (Solder Iron):

- Temperature at tip of iron: 350°C Max.
- Soldering Time: 3 seconds ± 1 sec.

Soldering Heat (DIP):



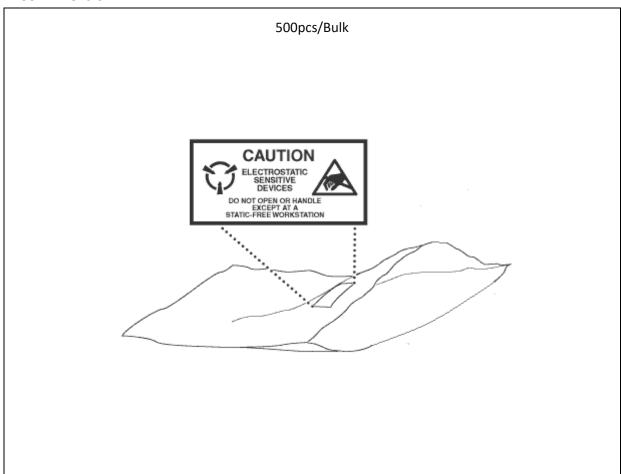
Note:

- 1. Maximum reflow soldering: 1 time.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a year. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

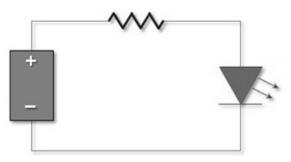
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	03/04/2023	Datasheet set-up.
A1.1	14/12/2023	Revise storage condition.